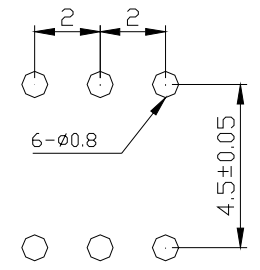
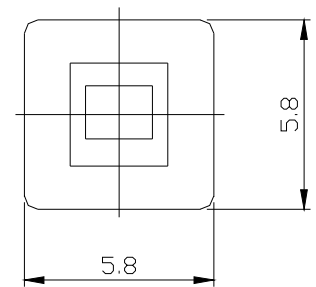
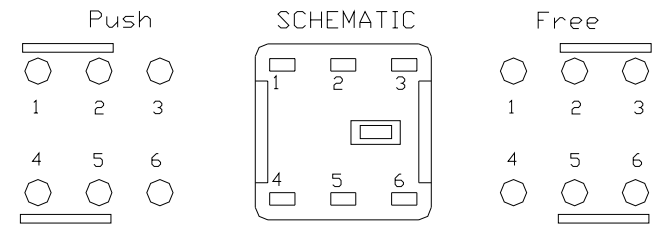


NO.	AREA	REVISION	DATE	NAME	ED.
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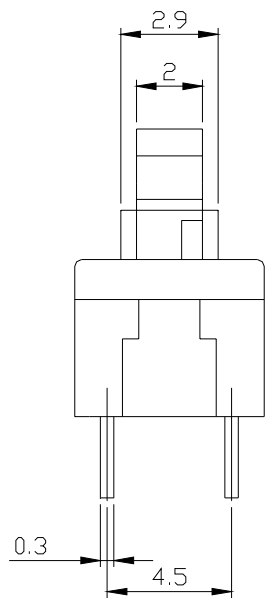
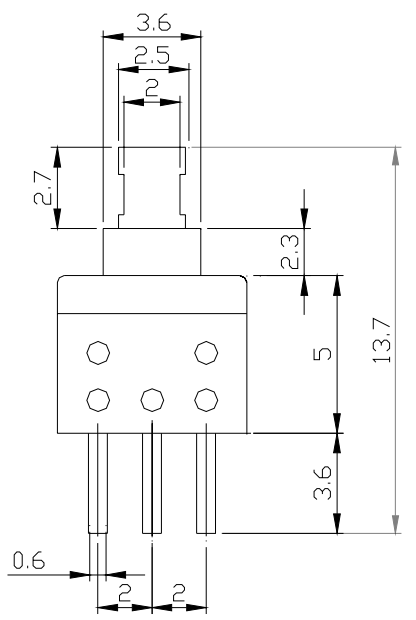


UP.C.B. LAYOUT

CIRCUIT DIADRAM



BOTTOM VIEW



MODEL NO.	Operating Mode		
HSP 2266	Self-Lock		
HSP 2266N	Non-Lock		
TITLE.	HSP-2266		
DWG. BY	04/19-'04	PART NO.	--
CHK. BY	04/19-'04	QUANTITY.	--
APP. BY	04/19-'04	COLOR	--
Up To 10mm±0.4	FINISH	--	
Above 10~100mm±0.6	MATERIAL	--	
Above 100mm±0.8	HARDNESS.	--	
HUA-JIE	SCALE	5 : 1	
	UNIT	MM	
	3RD	⊕	